

SBR10U45SD1, SBR12A45SD
Weight (mg): 1210.1392

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Si	7440-21-3	98.80%	0.88	10.68	988000	8720
		Ni	7440-02-0	1.20%			12000	106
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.71	8.6192	925000	6588
		Sn	7440-31-5	5.00%			50000	356
		Ag	7440-22-4	2.50%			25000	178
		Cu	7440-50-8	99.95%			999500	758418
Leadframe & Clip	OFC	Misc	-----	0.05%	75.88	918.25	500	379
		SiO2	14808-60-7	76.86%			768587	163131
Encapsulation	Epoxy	CNE EPOXY RESIN (C15H16O2)	29690-82-2	19.03%	21.22	256.85	190258	40382
		Brominated epoxy resin	68928-70-1	2.06%			20577	4368
		Antimony trioxide(Sb2O3)	1309-64-4	2.06%			20577	4368
Lead Plating Finish	Tin Solder	Sn	7440-31-5	100.00%	1.30	15.74	1000000	13007
				Total	100.00	1210.14		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables o EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos

Azo compounds

Cadmium and cadmium compounds

Certain Shortchain Chlorinated Paraffins

Chlorinated organic compounds

Hexavalent chromium compounds

Lead and lead compounds

Mercury and mercury compounds

Organic tin compounds

Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)

Ozone Depleting Substances - Class II (HCFCs)

Perfluorooctane Sulphonate (PFOS) or related compounds

Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including **DecaBDE**

Polychlorinated Biphenyls (PCBs)

Polychlorinated Naphthalenes (> 3 chlorine atoms)

Radioactive Substances

Tributyl Tin (TBT) and Triphenyl Tin (TPT)

Tributyl Tin Oxide (TBTO)

This product or product family meet REACH requirements for chemicals designated by the European Chemicals Agency (ECHA) as Substances of Very High Concern (SVHC) appended below:

Anthracene

4,4'- Diaminodiphenylmethane

Dibutyl phthalate (DBP)

Cyclododecane

Cobalt dichloride

Diarsenic pentaoxide

Diarsenic trioxide

Sodium dichromate, dihydrate

Bis (2-ethyl(hexyl)phthalate) (DEHP)

Hexabromocyclododecane (HBCDD)

Bis(tributyltin)oxide (TBTO)

Lead hydrogen arsenate

Triethyl arsenate

Benzyl butyl phthalate (BBP)

5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)

Alkanes, C10-13, chloro (SCCPs - Short Chain Chlorinated Paraffins)

RoHS Exemption 5 for Pb in glass in electronic components and 7a for Pb in High Temperature, High %Pb in Solder is applied